

# Making progress vs strategy

## Ian Thornton, Head of Investor Relations



Arm is a subsidiary of  SoftBank

# Arm update

Arm refresher

H1 update – Increasing revenues and investments

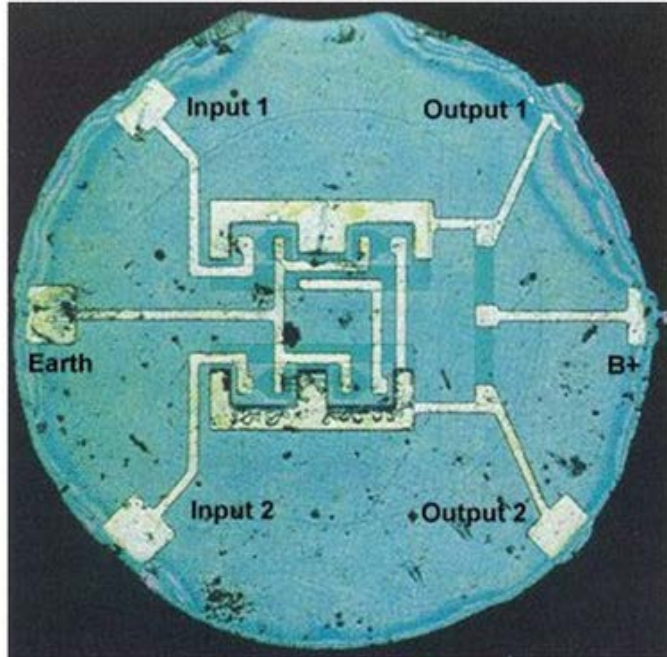
Progress vs strategy

- Arm in servers
- AI at the edge
- Autonomous vehicles

# ARM overview

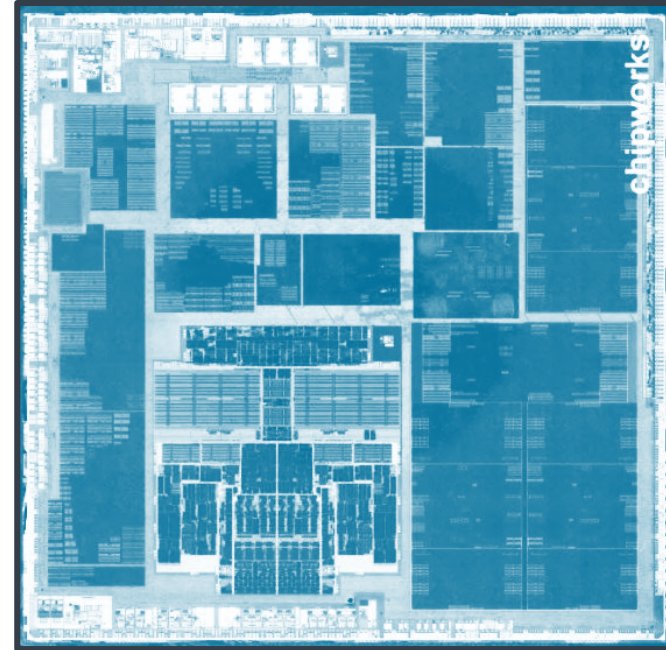
# Chip design – then and now

1961



Four transistors  
One engineer

Today



Two billion transistors  
Thousands of engineers

# A system-on-chip contains multiple blocks of IP

**Main processor** for running the operating system, applications and user interface

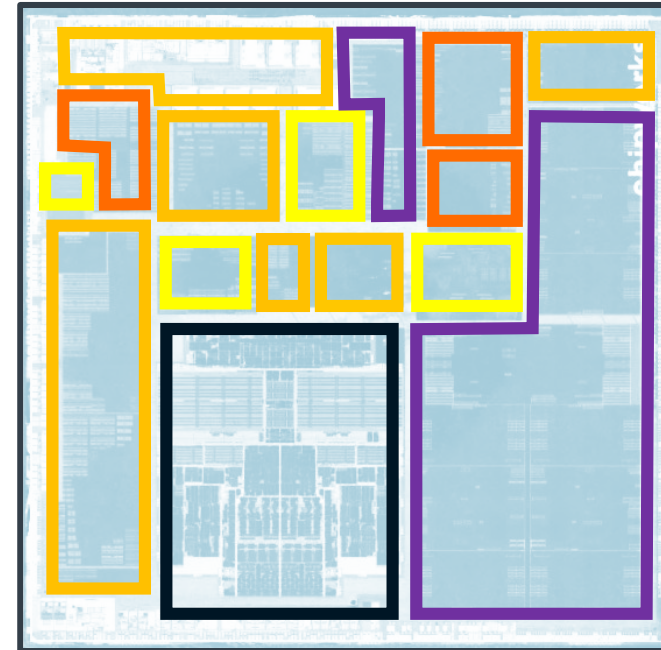
**Graphics processor** for generating images

**Accelerators** for frequently-used compute workloads, e.g. image processing, encryption, vision

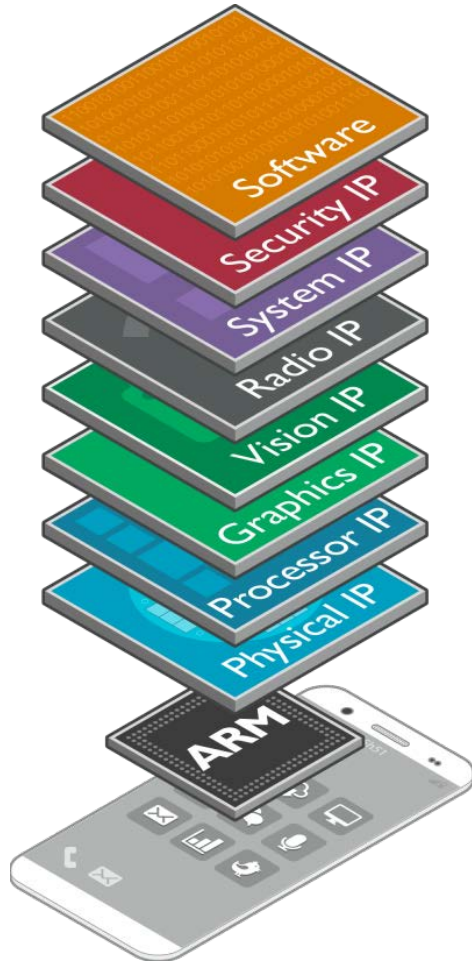
**Radio controllers** for mobile, wifi, Bluetooth, GPS

**Hardware controllers** for the display, memory, image sensors, power supply, etc

**Input/Output** interfaces for USB, Ethernet, etc



# ARM's current business



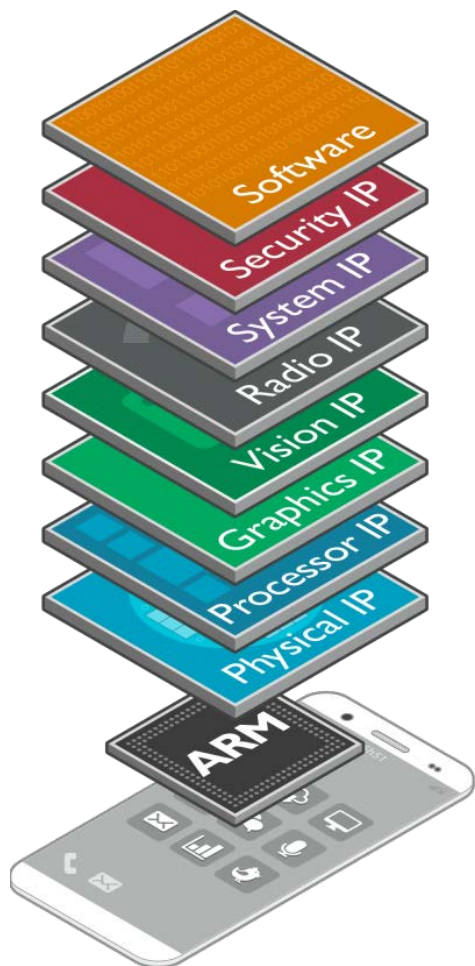
ARM develops **intellectual property** (IP) blocks which are used in silicon chips

Our partners combine ARM IP with their own IP to create complete chip designs

We earn **license fees** when we deliver ARM IP to our partners and **royalties** when our partners ship chips that contain ARM IP

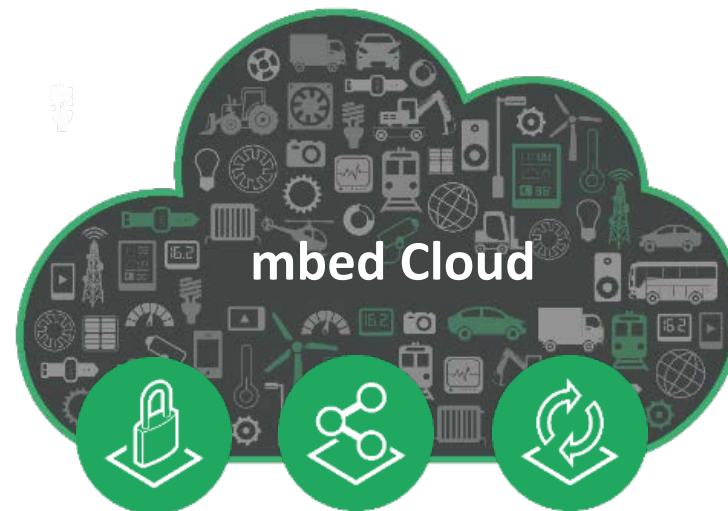
Highly **profitable** and **cash generative**

## Accelerating investment to increase share gains



Generating  
**\$500m**  
free cash flow  
(2017 forecast)  
and growing

## Investing to create new revenue streams



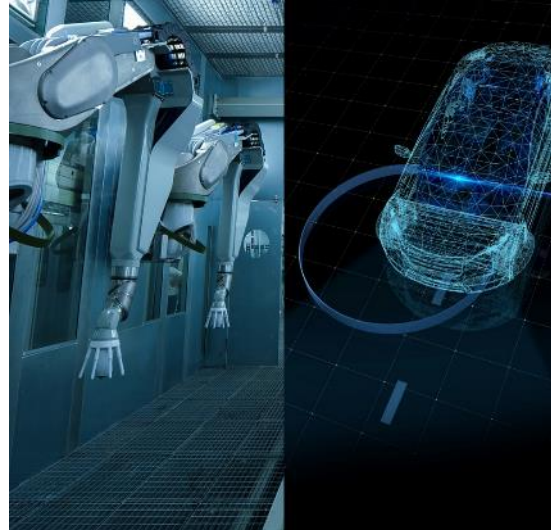
mbed Cloud Partners



# Technology trends that will redefine all industries



Artificial Intelligence in every device



Autonomous machines



Augmented reality



Hyperscale cloud and connectivity



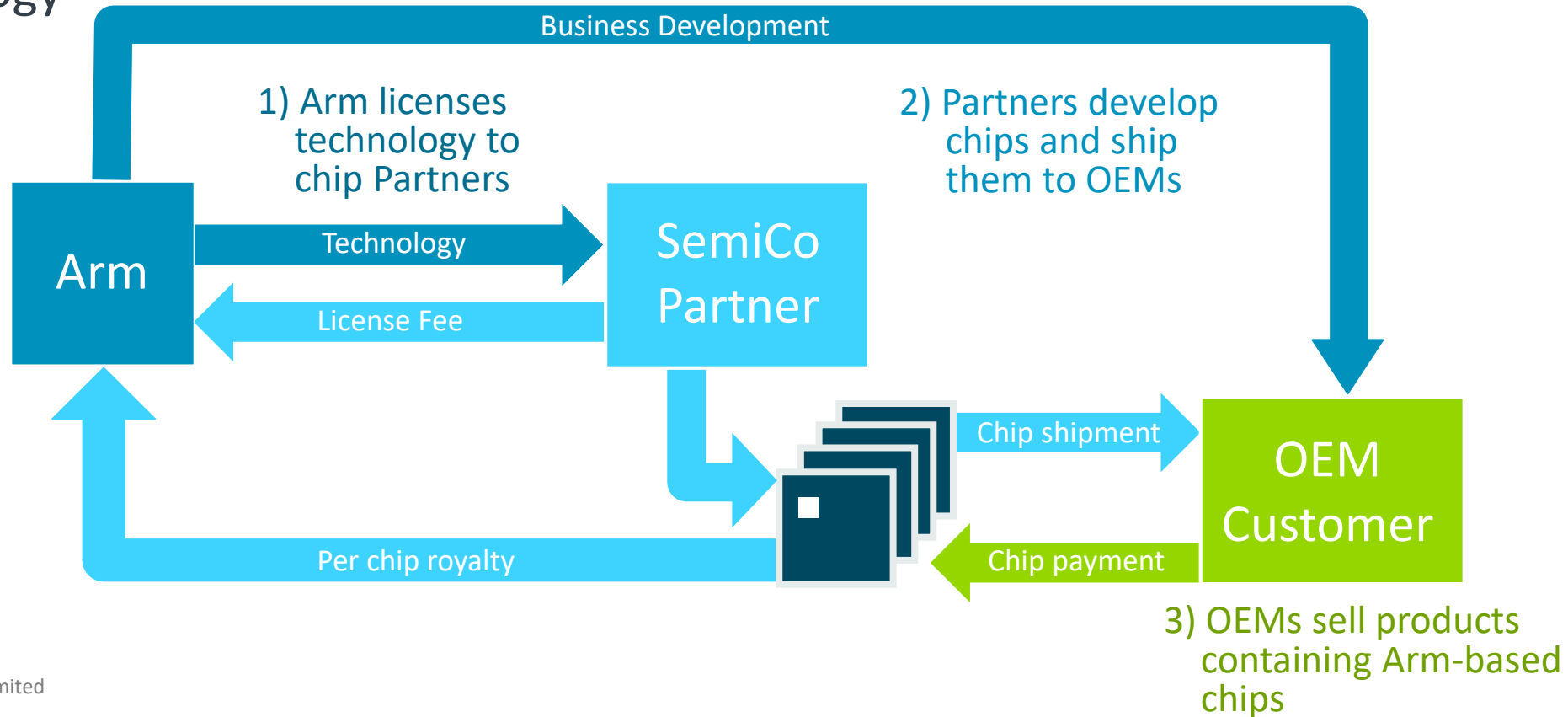
Security and Privacy



# Arm's business model

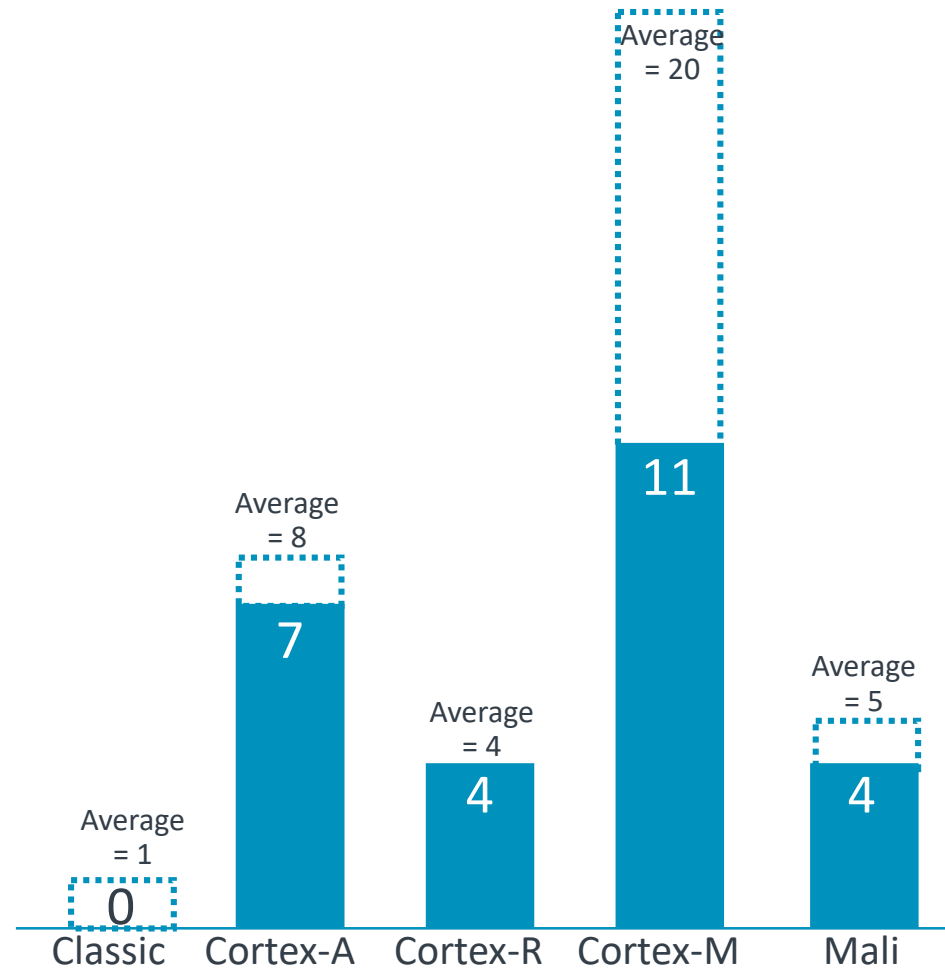
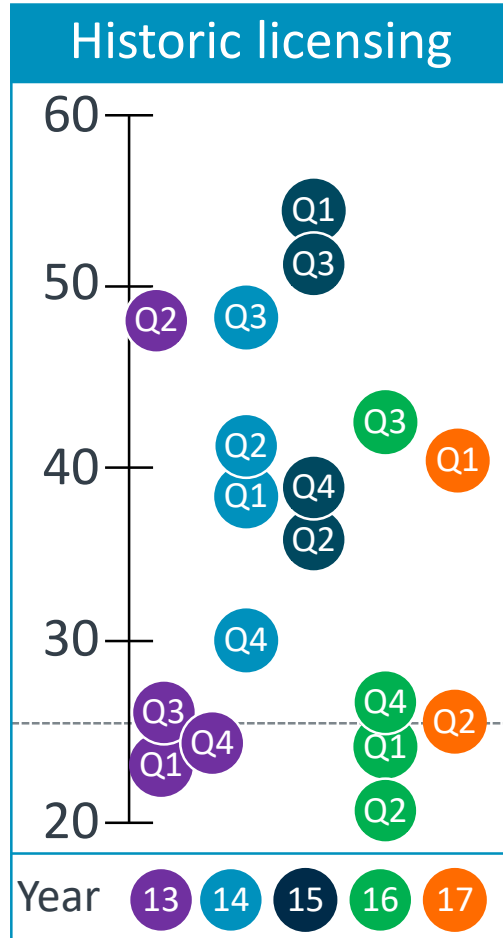
Arm develops technology that is licensed to semiconductor companies

Arm receives an upfront license fee and a royalty on every chip that contains its technology



# Licensing

# Q2 Licensing: 26 is the low-end of the normal range





DesignStart for Cortex-M0 and Cortex-M3

**Faster access  
to IoT processors**

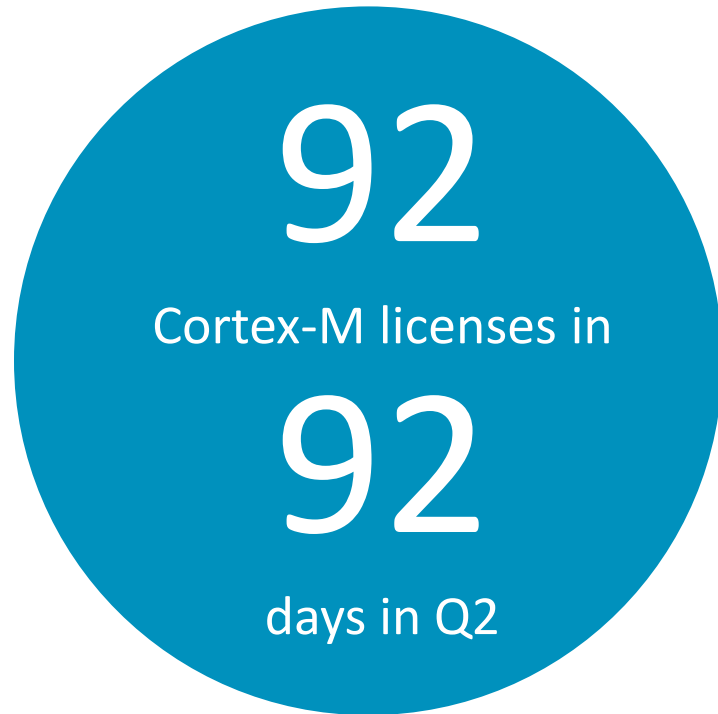
**No upfront fee**



**Accelerating  
the next trillion  
IoT devices**

\*DesignStart gives companies easy access to Arm IP. There is no upfront license fee, the partner pays royalties once chips enter production.

# DesignStart – Enabling the entire industry to build chips

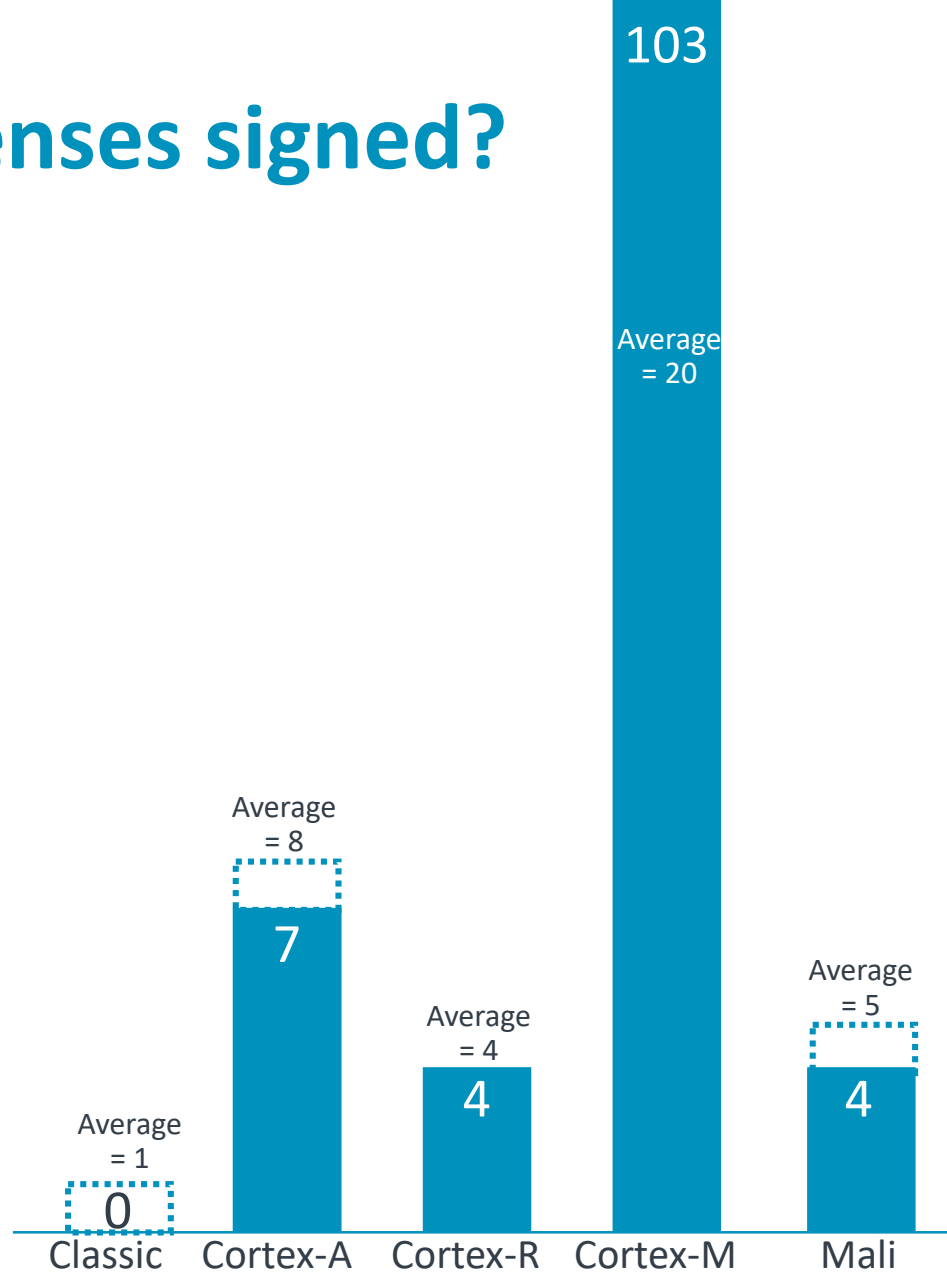
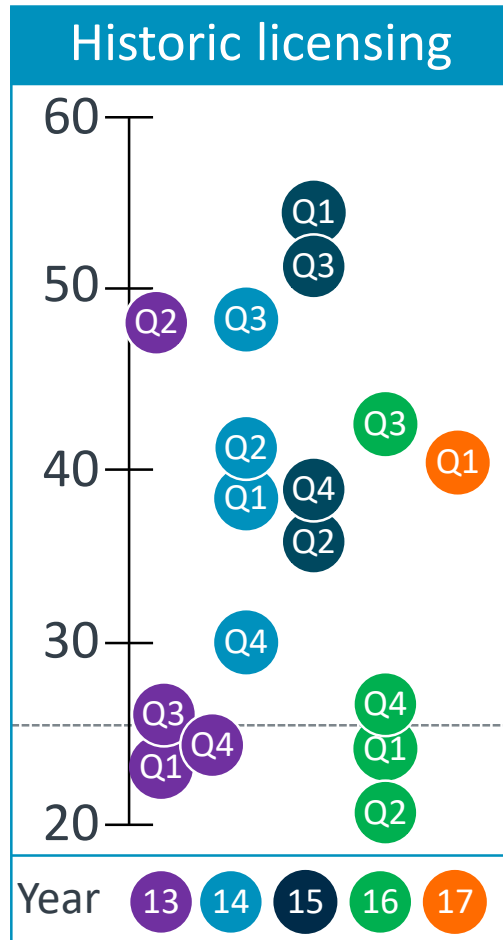


**DesignStart Pro**  
Launched end June 2017  
License-fee free; royalty bearing



**DesignStart Eval**  
Launched end June 2017  
No fees. Evaluation only.  
Optimised for FPGA

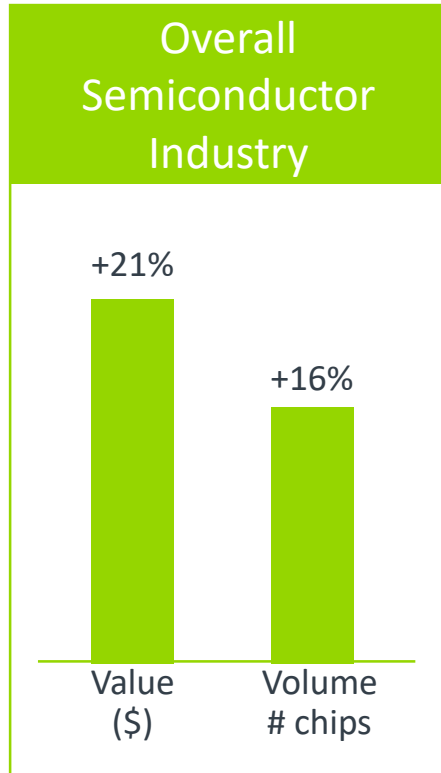
# Q2 Licensing: 118 licenses signed?



# Royalties

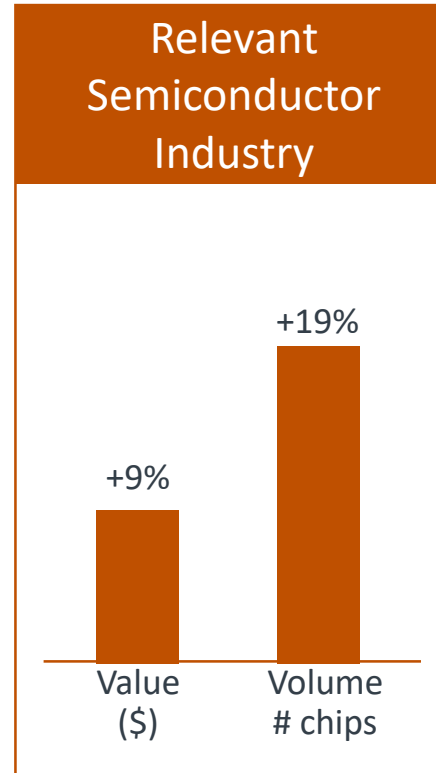
# Industry growth vs Arm growth (for Q2 2017)

**\$190bn**



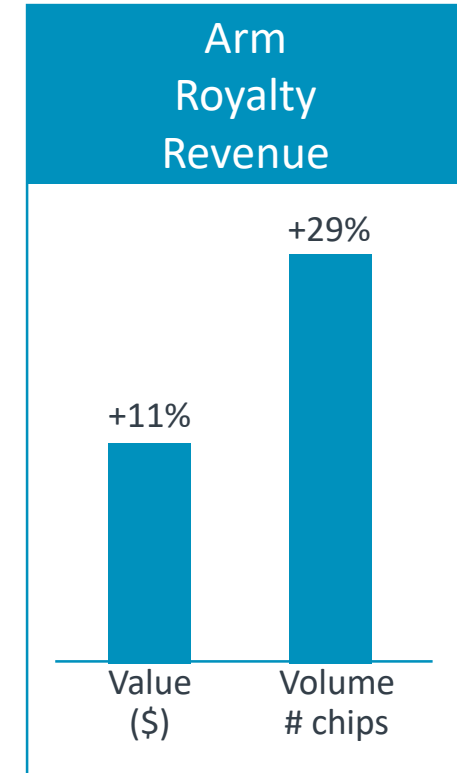
Strong growth in memory and graphics for data centre

**\$80bn**



Strong growth in MCUs; slower growth in apps for mobile

**\$0.5bn**

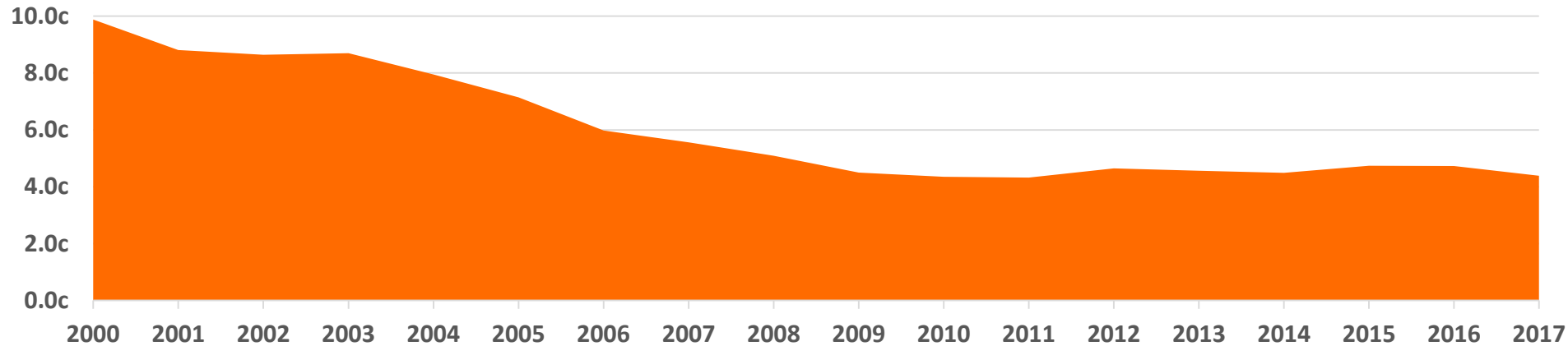


Arm gaining share in embedded Royalty rate increasing



# Is declining average royalty revenue per chip a concern?

Average royalty per chip



## Drivers of average

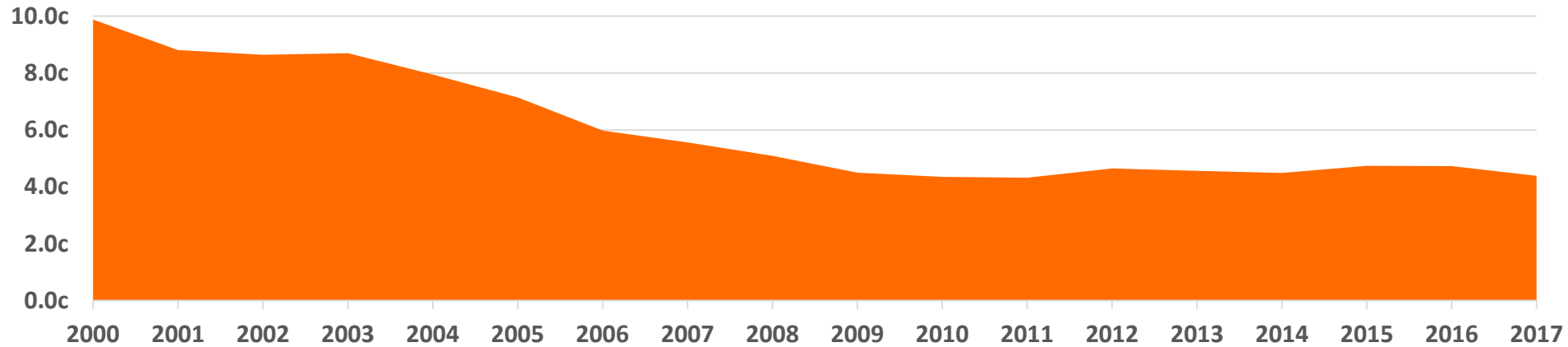
- Chip related: Average sales price of the chip; Arm content per chip
- Arm related: Average royalty rate per processor; increased content multipliers
- Customer mix related: Which customers are winning share
- Market mix related: Which markets are growing fastest

Second

Biggest impact on average over the long term

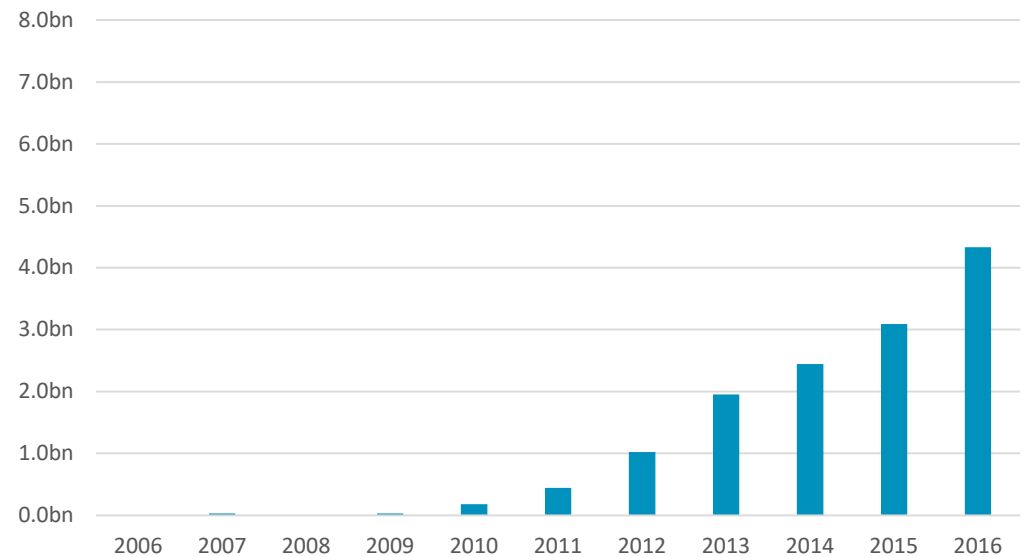
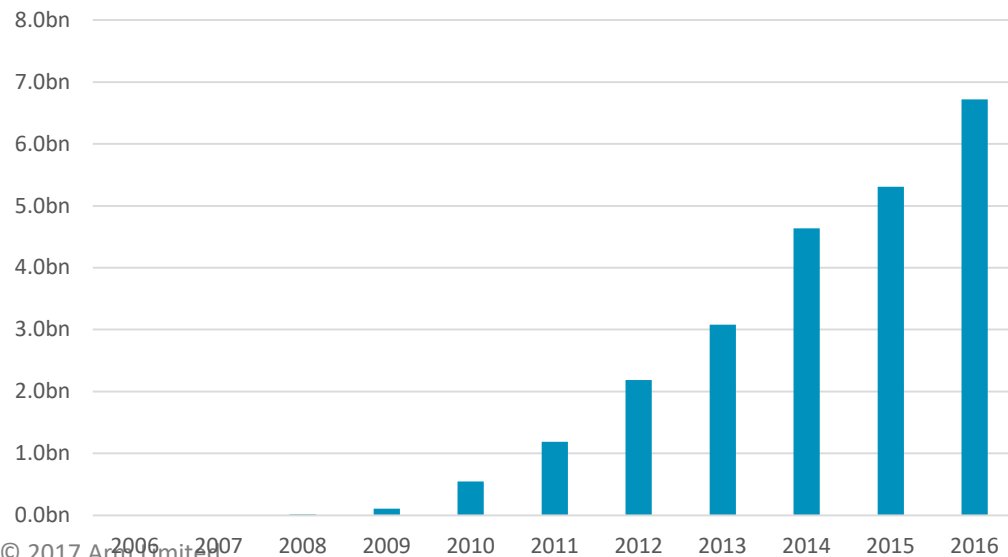
# Is declining average royalty revenue per chip a concern?

Average royalty per chip



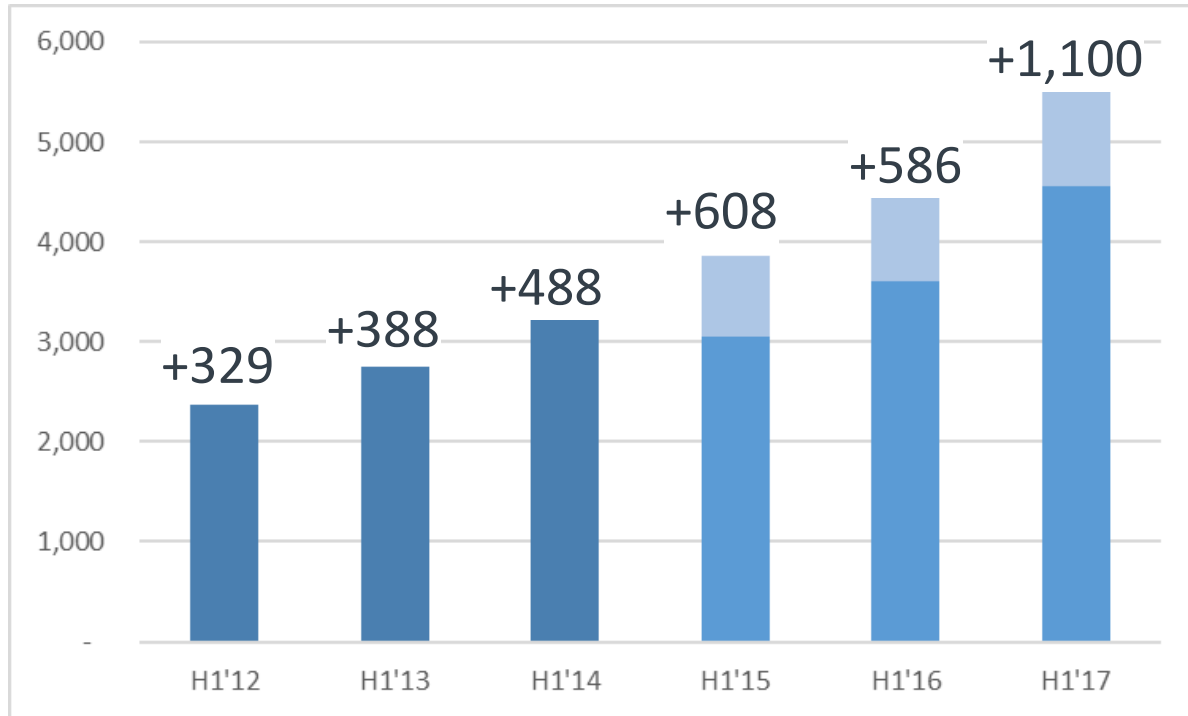
Cortex-M

Cortex-A



# Investments Profitability

# Investing in engineering to increase productive output



Arm recruitment is running at around 2x previous run rate

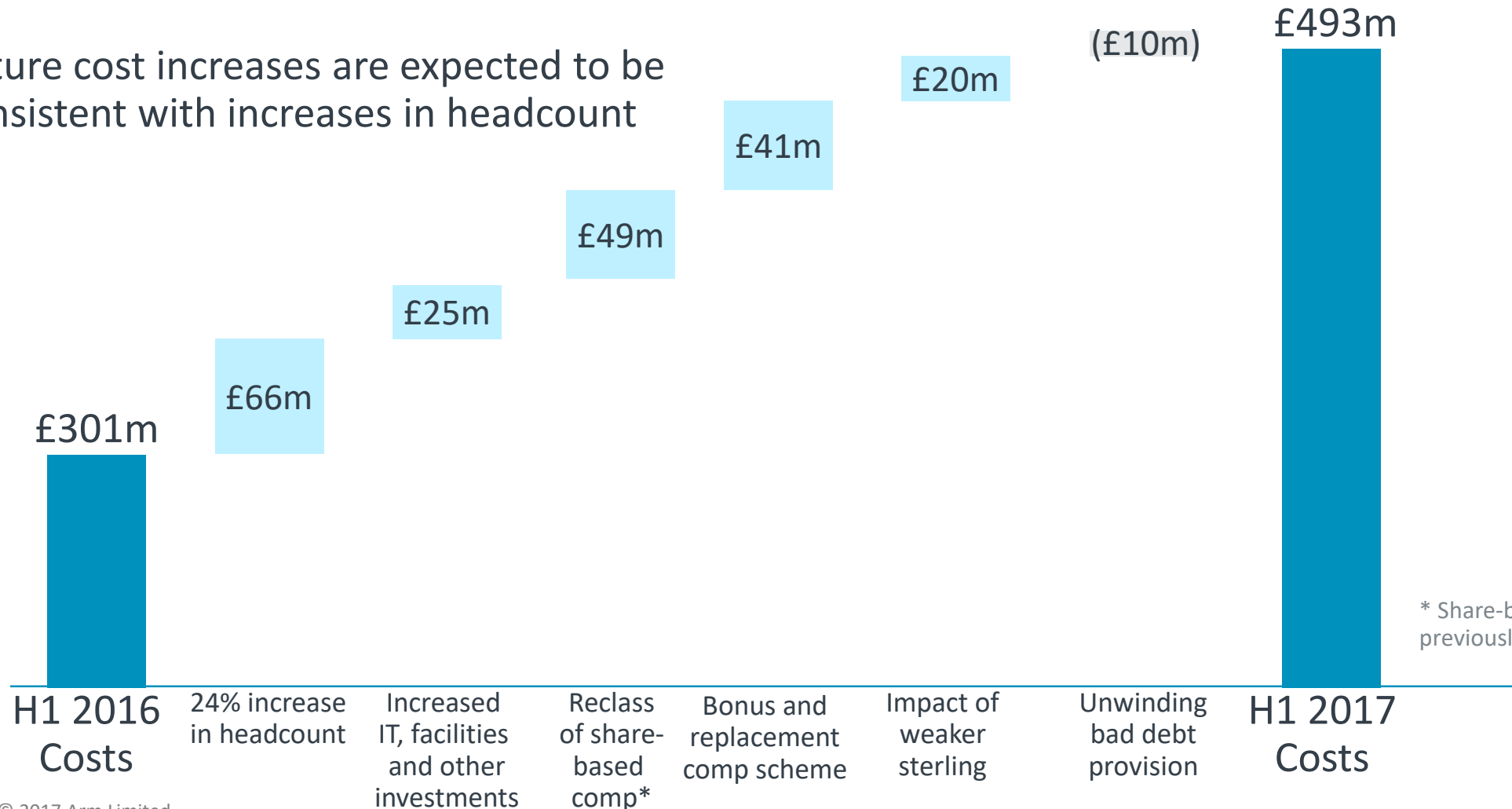
Focus on retaining quality as well as quantity; and on cultural and organisational integration

Will need to sustain this run rate for next 2-3 years

# Investing in people, infrastructure to create new products

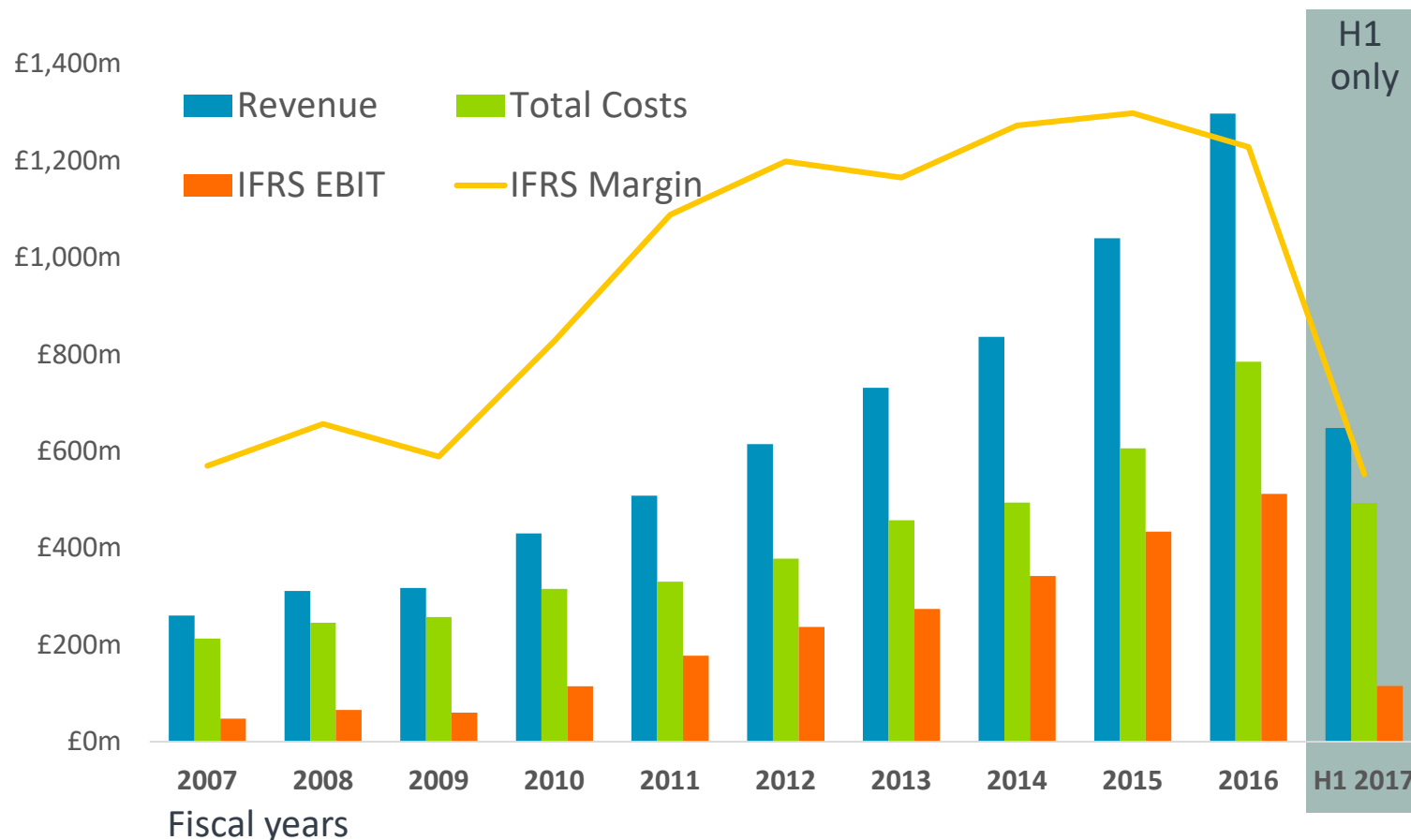
Costs were higher in H1 2017 as Arm expands R&D capability

Future cost increases are expected to be consistent with increases in headcount



\* Share-based compensation was previously included in IFRS "other costs"

# Revenues, profits and profitability



Over the past 10 years Arm's revenues grew faster than costs

## H1 2017 vs H1 2016

- Revenues +17%
- Headcount +24%
- Costs +64%
- Profits -39%
- IFRS Margin \* 18% vs 35%

\* Excluding impact of currency fluctuations as USD/GBP went from 1.27 to 1.32. This contributed to £37m of non-cash costs due to revaluation of long-term contracts. Including these IFRS Margin would be 12%.

Note: Excludes certain one-offs

- 2013: Write down of MIPS patents (£100m)
- 2016: Execution costs associated with SoftBank acquisition


# Progress vs strategy

Artificial Intelligence in every device

Autonomous machines

Augmented reality

Hyperscale cloud and connectivity

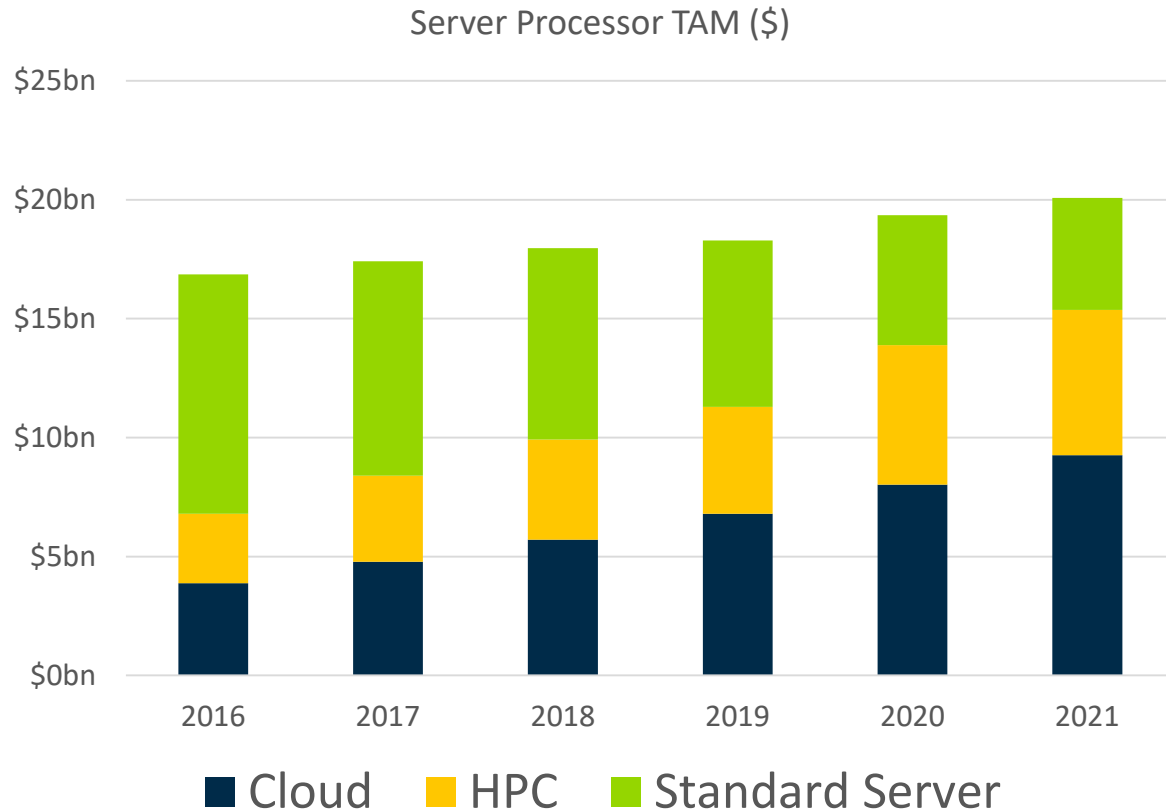
 Security and Privacy

The background is a detailed, blue-tinted image of a server circuit board. A central processor chip is highlighted with a bright, glowing effect. The board is densely packed with various components, including capacitors, resistors, and other integrated circuits, all connected by a complex network of traces. The overall aesthetic is technical and futuristic.

# Arm in servers



# Server market is changing



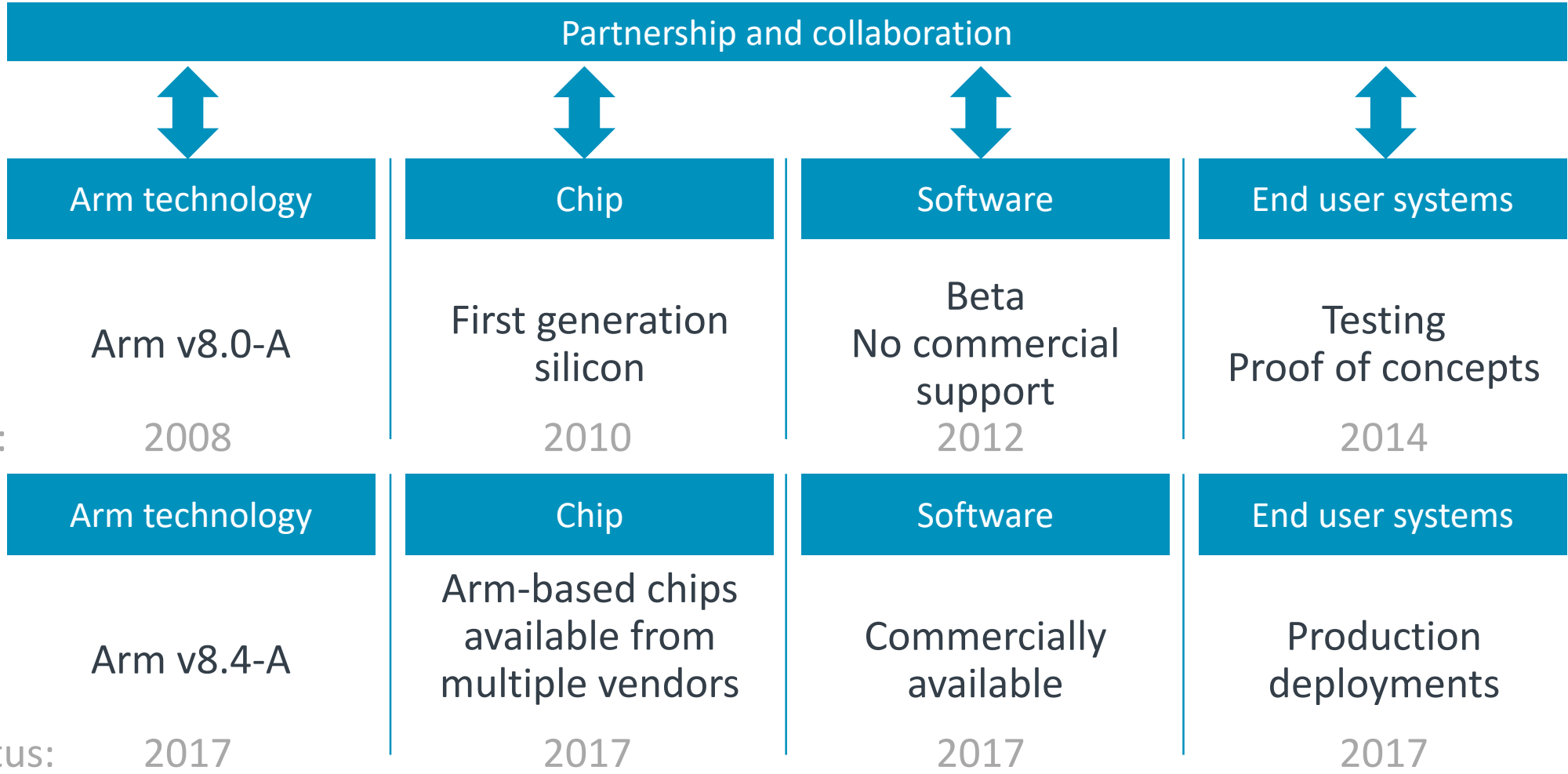
Standard enterprise

High-performance computing

















Cloud

ARM focused on Cloud/HPC

# Arm's strategy to win share in servers



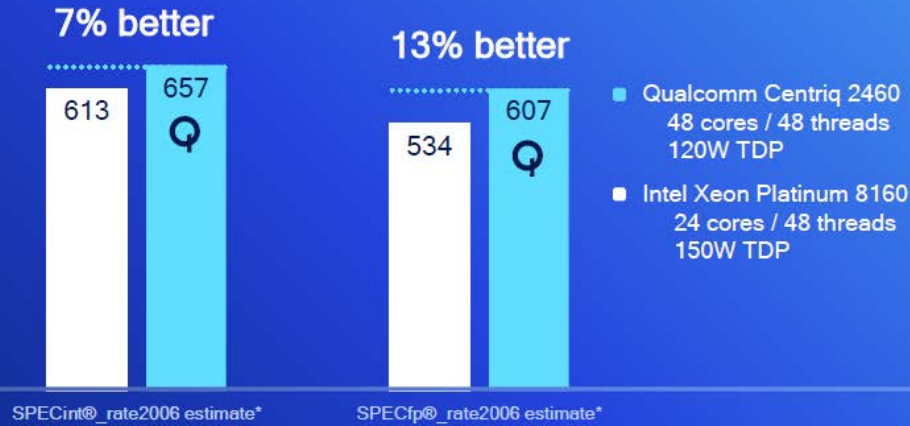
# Arm technology

	Arm v7-A	Arm v8.0-A	Arm v8.2-A	Arm v8.4-A
	<ul style="list-style-type: none"> <li> Cortex-A15</li> <li> Cortex-A9</li> <li> Cortex-A7</li> <li> Cortex-A5</li> </ul>	<ul style="list-style-type: none"> <li> Cortex-A72</li> <li> Cortex-A57</li> <li> Cortex-A53</li> <li> Cortex-A35</li> </ul>	<ul style="list-style-type: none"> <li> Future</li> <li> Cortex-A75</li> <li> Cortex-A55</li> <li> Future</li> </ul>	<ul style="list-style-type: none"> <li> Future</li> <li> Future</li> <li> Future</li> <li> Future</li> </ul>
Architecture released	2004	2011	2015	2017
New Capability	<ul style="list-style-type: none"> <li>Multi-core processing</li> <li>Multimedia acceleration</li> </ul>	<ul style="list-style-type: none"> <li>64-bit computing</li> <li>Improved multi-core</li> <li>Improved multimedia</li> </ul>	<ul style="list-style-type: none"> <li>Improved multimedia</li> <li>Improved multi-core</li> <li>Improved error management</li> <li>Acceleration for AI/ML</li> <li>Acceleration for virtualisation</li> </ul>	<ul style="list-style-type: none"> <li>To be announced</li> </ul>

# Arm-based chips available from multiple vendors



# Arm silicon is competitive with current technology

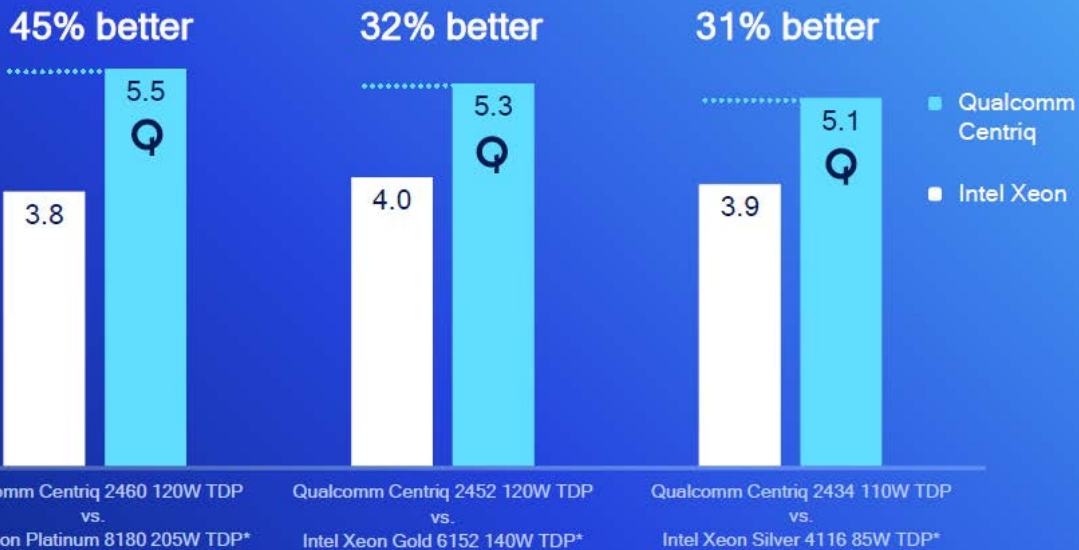


## Performance

24

## Performance per thread

25



## Performance per Watt

27

## Performance per dollar

Qualcomm Centriq 2400 processors

# Arm server software is commercially available



All the major open source operating systems are now commercially available for Arm-based servers

# Arm servers are being deployed by cloud companies



### 2016 CUSTOM SILICON

- Custom Si & 25GbE
  - 2x 25GbE cheaper & higher bandwidth than 40GbE
- Amazon Annapurna ASIC
  - Second generation Enhanced Networking
  - AWS controls silicon, hardware & software
  - AWS pace of innovation
- Instance peak bandwidth to 20GbE
  - Small instance peak bandwidth at 10GbE
  - Most instance types going forward




规格特点

- 处理器: 2.1 GHz 主频的 Cavium CN800 (ThunderX) 处理器
- 高网络性能, 450 万 PPS 网络收发与能力
- 支持 SSD 云盘和超快云盘
- 适用于多核高吞吐场景, 低成本计算需求

实例规格

实例规格	vCPU	内存 (GB)	本地存储 (GB)	网络带宽能力 (出/入) (Gbps)	网络收发能力 (出/入) (万 PPS)	多队列
ecs.ebna1.2xlarge	96	256	无	10	450	16

\* 网络收发性能测试方法参见: [网络性能测试方法](#), 开启所有队列。  
[返回目录](#) 查看其他实例规格。



## 黑石ARM服务器

黑石 ARM 服务器 (CPM for ARM) 是种 ARM 服务器的裸机租赁服务。黑石 ARM 实例使用了 ARMv8 架构, 它能提供更大的内存容量和更多的物理内核, 具有更强的性能和更有竞争力的 TCO (总体拥有成本); 且天然兼容移动端应用, 无需进行指令集的转译。如果您的业务属于高开发或者移动端场景, 黑石 ARM 服务器将是非常睿智的选择。

[立即申请](#)

☞ 申请使用资格, 将有专人为您提供服务与报价




### OPTIMIZING ARM64 SERVERS FOR MICROSOFT'S CLOUD SERVICES

Evaluating multiple ARM64 servers (Qualcomm, Cavium and others)

Ported Windows Server for Azure internal use only

Easy deployment with Project Olympus compliant motherboards





arm

Artificial intelligence  
at the edge



# Distributing intelligence everywhere

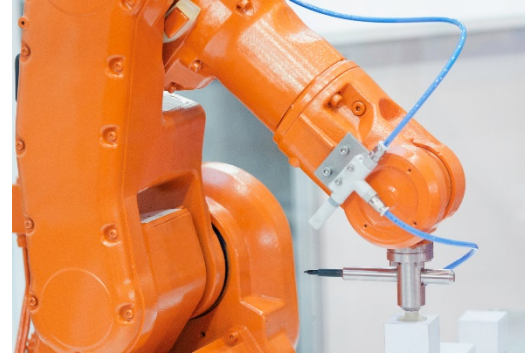
## Mobile



## Automotive



## Robotics



## Drones



## IoT



## Home, surveillance & analytics



## VR/MR



## Shipping & logistics





# From the cloud to the edge



Security



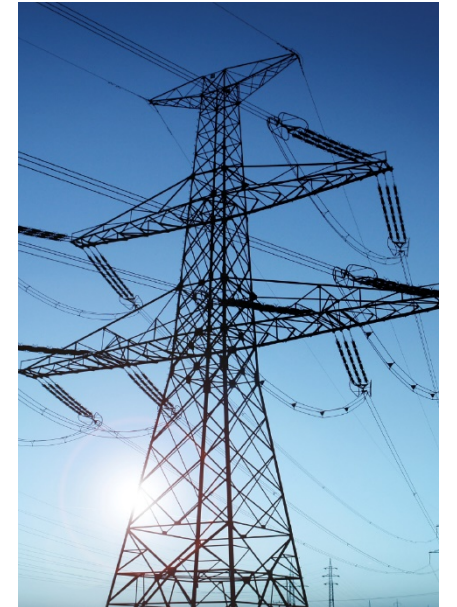
Privacy



Latency



Bandwidth



Power and Cost

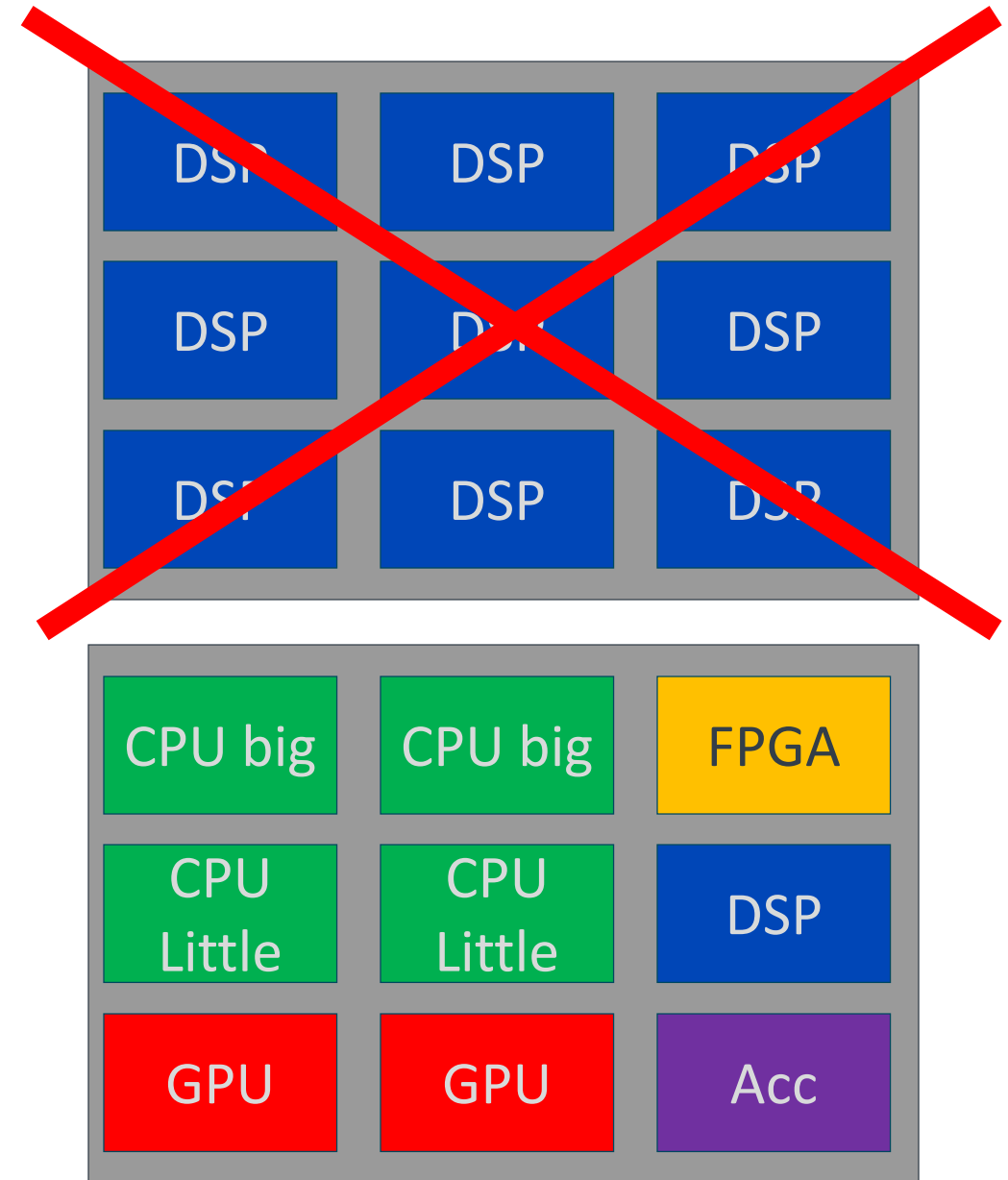
# Heterogeneity is necessary

There is no one size fits all solution

Need multiple types of processors to handle this

Fixed function works when requirements known in advance, algorithm is well understood, and high performance needed

Programmable cores are essential



# Arm's approach to AI

Machine Learning applications

Domain-specific libraries + ML frameworks: TensorFlow, Caffe, MXNet, etc.

Tools and libraries from Arm

CPUs + GPUs + ISPs + CV engines

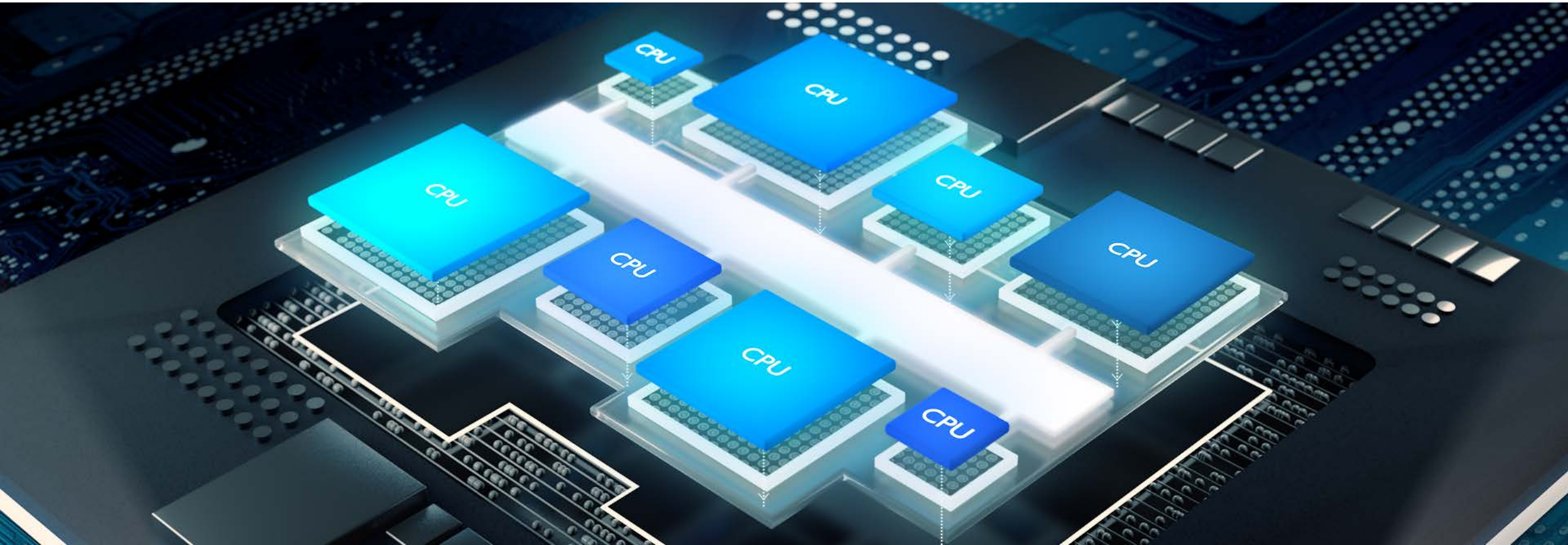
DSP

FPGA

ACC

# ARM DynamIQ – Multicore redefined

ARM DYNAMIQ



New single cluster design

Greater flexibility

Redesigned memory  
sub-system

Advanced compute  
capabilities

# Journey of the autonomous automotive

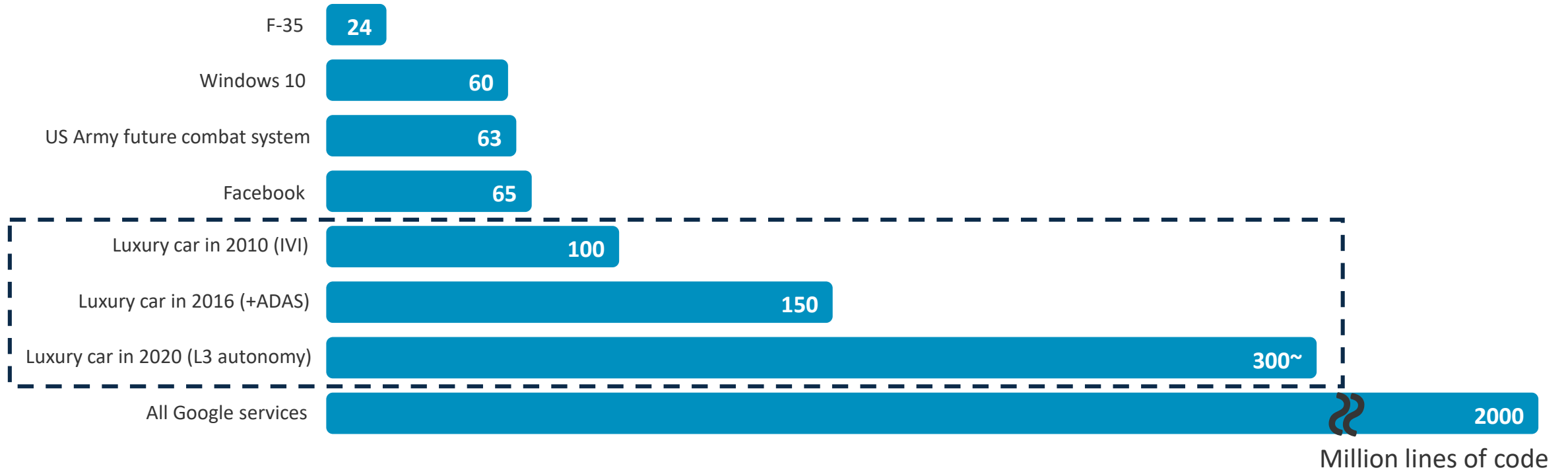
arm

**“90% of automotive innovation  
comes from electronics  
(semiconductors) and software.”**

– Audi at CES Asia



# Cars run on code



# Automotive compute in 2020

## Cockpit

**~50,000 DMIPS**

Audio Visual, Maps, Traffic, Toll payment, Google services  
Rear entertainment, Voice recognition, Gesture control, Cluster and HUD

## Connected Gateways

**~20,000 DMIPS**

LTE 5G, WiFi, Bluetooth  
connecting to CAN FD, LIN, Flexray, Ethernet

## Body Electronics

**<10,000 DMIPS**

HVAC, Lighting, Doors, Electric seat, Windows, Mirrors, Cameras, Seat belt, Air bag, BCM

## High-end smartphone

**30,000-50,000 DMIPS**

Main applications processor, WiFi, modem, sensors, etc.



## Semi Autonomous

**~350,000 DMIPS**

Level 3 autonomy, Radar / image processing, Collision avoidance, Pre-crash, Cruise control, Lane departure, Parking

## Chassis

**~15,000 DMIPS**

EPS, ABS/EBS, Active VDC, EPB

## e-Powertrain

**~15,000 DMIPS**

Main Motor control, Transmission, Engine control, Generator/E-water pump  
Battery management



# Timeline for autonomous driving

2016

2018

2020

2025



**Advanced**

- Several control functions
- Collision Avoidance Steering (Low speed)
- Advanced camera systems
- CAN FD (10Mbps)
- Sensor fusion

**HIGHLY AUTOMATED**

- All-round collision avoidance
- Limited automated driving
- Ride sharing
- Camera systems with 4k
- Ethernet bus (1Gbps)

**AUTONOMOUS**

- Start of fully automated driving
- High speed all-round collision avoidance
- Car sharing
- Connected vehicle to vehicle
- Interactive

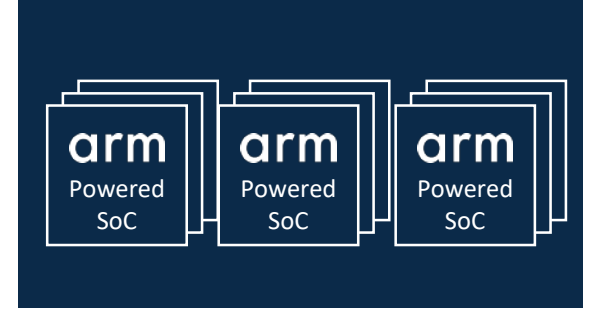
Relative to 2016 Vehicles

20X performance  
10X Data rate

40-50X performance  
100X Data rate

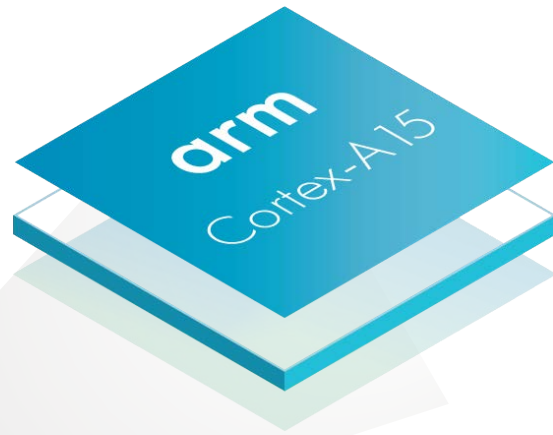
100X performance  
400x Data rate

Scalable processing solutions

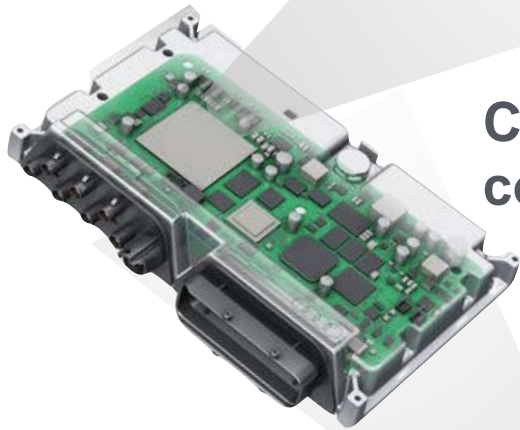




# Powering the world's first self-driving car NVIDIA Tegra K1



Central driver assistance controller "zFAS"



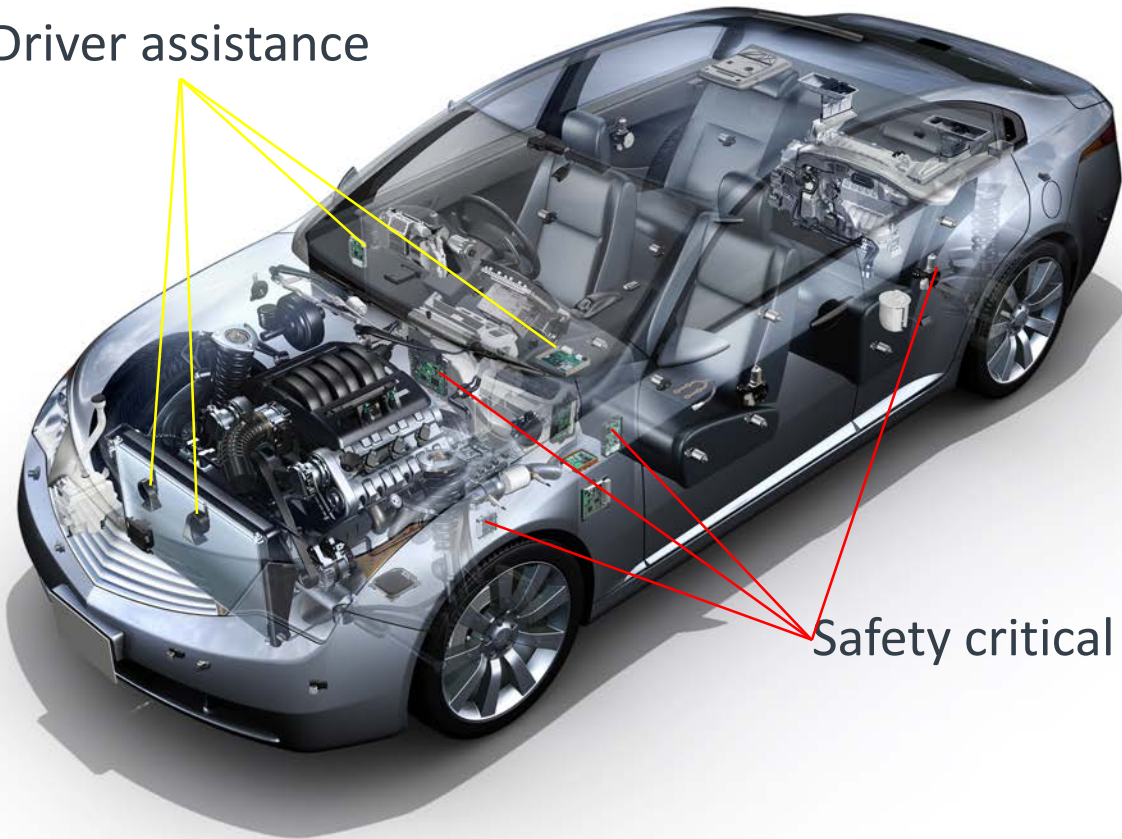
New Audi A8

# Denso licenses first ever Arm processor (Cortex-R52)

Targeting advanced driver assistance and safety critical systems

# DENSO

Driver assistance



Safety critical

Cortex-R52: Highest performance real-time processor

First processor with embedded virtualisation to simplify software consolidation

Designed for functional safety systems

Thank You!

Danke!

Merci!

谢谢!

ありがとう!

Gracias!

Kiitos!

감사합니다

धन्यवाद

arm